

REMARKS

Claims 1-19 are pending in the application. Claims 1 and 15 have been amended to specify that the integrated circuit is connected directly to the conductor tracks. Support for the amendments to claims 1 and 15 may be found, for example, on page 7, lines 1-6 of the specification. No new matter has been added.

Objections to the Claims

Claim 1 is objected to over lack of antecedent basis for the phrases "the measured signals" and "the flip chip type." Claim 1 has been amended to provide antecedent basis for these phrases. Applicant respectfully requests that the objection to claim 1, as amended, be withdrawn.

Claims Rejections 35 U.S.C. 102

Claims 1-19 are rejected by the Examiner under 35 U.S.C. 102(b) as being anticipated by Davidson (5,414,355). The Examiner's rejection has been carefully considered. In response to the Examiner's rejection, Applicant has amended claims 1 and 15 to specify that the integrated circuit is connected directly to the conductor tracks.

Claim 1 recites, in part, that basic component (10) is embodied as an MID (Molded Interconnect Device). In the rejection of claim 1-14, the Examiner asserts that Davidson discloses a housingless integrated circuit mounted on a basic component provided with conductor tracks and embodied as an MID (Molded Interconnect Device) component.

Applicant respectfully disagrees with the Examiner that the basic component disclosed by Davidson is embodied as an MID. A MID device comprises an injection-molded modified plastic substrate made of two materials. One material forms the basic body and another is metallizable and forms a conductor track layout. A MID can also be

made using a hot press procedure in which an injection molded part is placed into a stamping press. A surface modified metal foil is simultaneously cast and bonded to the injection molded part using pressure and heat. MIDs can also be made using laser structuring.

Davidson discloses a sensor in which the magnetically sensitive component 38 is disposed on the front end of a carrier 10. The carrier 10 has a plurality of conductors 12, 14, 16 molded within its body (column 3, lines 55-58). The substrate is made of ceramic material or, alternatively, can be a flexible circuit or printed circuit board (column 2, lines 65-68). A carrier as disclosed in Davidson containing conventionally molded conductor tracks would not be viewed by one skilled in the art as a MID.

Claim 1, as amended, recites that the integrated circuit (32) is connected directly to the conductor tracks (28, 30). Column 4, lines 15-23 in Davidson discloses that the magnetically sensitive component 38 is disposed at the front end of carrier 10 and attached to substrate 40. The substrate 40 is provided with a plurality of conductive portions that permit the magnetically sensitive component 38 to be connected in electrical communication with electrical conductors 12, 14, and 16. Consequently, in the sensor disclosed by Davidson, the integrated circuit is not directly connected to the conductor tracks.

Applicant respectfully requests that the rejection of claims 1-14 as being anticipated by Davidson be withdrawn because Davidson does not disclose a sensor comprising a MID or an integrated circuit connected directly to conducting tracks as recited in the present claims.

With regard to claims 15-19, claim 15 has been amended to include the limitation that the integrated circuit is connected directly to conductor tracks 12, 14, and 16. Davidson does not disclose such a direct connection as explained in the arguments presented in the preceding paragraphs. Applicant respectfully requests that the rejection of claims 15-19 as being anticipated by Davidson be withdrawn because

Davidson does not disclose a sensor comprising an integrated circuit connected directly to conducting tracks as recited in the present claims.

Conclusion

The application in its amended state is believed to be in condition for allowance. Action to this end is courteously solicited. Should the Examiner have any further comments or suggestions, the undersigned would very much welcome a telephone call in order to discuss appropriate claim language that will place the application into condition for allowance.

Respectfully submitted,



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